

PATENT



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Case	Docket No	SS-714-01
Date	June 19	, 2000

COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231

Sir:

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Transmitted herewith for filing is the patent application of:

Inventor:

VLADIMIR VAGANOV

For:

METHOD FOR FABRICATING MICROSTRUCTURES WITH DEEP ANISOTROPIC

ETCHING OF THICK SILICON WAFERS

Inclosed are

;#1.	ICIOS	eu are:		
10 17—	24	Pages of specification	1 Pages of abstract 18 Pages of cl	Laims
I	16	Sheets of drawing	X_formalinformal	
<u>.</u>	Х	An assignment of the invent	tion toEcotech International, submitted wi	<u>th</u>
3)		separate transmittal		
		A certified copy application	n(s)	
رقمأ			from which priority is claimed.	
D				

CLAIMS AS FILED				
	NUMBER FILED	NUMBER EXTRA	RATE	BASIC FEE \$690.00
TOTAL CLAIMS	115 - 20 =	95	x \$ 18.00	\$1,710.00
INDEPENDENT CLAIMS	3 - 3 =	0	x \$ 78.00	0
Multiple Dependent Claims, if any 0 x \$260.00 0				

Filing Fee \$ 2,400.00

 $\overline{\mathbb{X}}$ A verified statement that this is a filing by a small entity is attached. fee due is fifty percentum of the above. The

Filing Fee \$ 1,200.00

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A check	in the amount of	_	, /	

THOMAS E. SCHATZEL Reg. No. 22/611

Date: 06-19-00

Attorney for Applicant

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